

- ✧ Low profile package
- ✧ Built-in stain relief, ideal for automatic placement
- ✧ Fast switching for high efficiency
- ✧ High temperature soldering:
260°C/10 seconds at terminals
- ✧ Plastic material used carries Underwriters Laboratory Classification 94V-0
- ✧ Meet MSL level 1, per J-STD-020D,
lead free maximum peak of 260°C
- ✧ Green compound with suffix "G" on packing code & prefix "G" on datecode



Mechanical Data

- ✧ Case: Molded plastic
- ✧ Terminal: Pure tin plated, lead free
- ✧ Polarity: Indicated by cathode band
- ✧ Packing: 12mm tape per EIA STD RS-481
- ✧ Weight: 0.064 grams

Ordering Information (example)

Part No.	Package	Packing	Packing code	Packing code (Green)
BYG20D	SMA	1.8K / 7" REEL	R3	R3G

Maximum Ratings and Electrical Characteristics

Rating at 25 °C ambient temperature unless otherwise specified.

Parameter	Symbol	BYG20D	BYG20G	BYG20H
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	200	400	600
Maximum RMS Voltage	V_{RMS}	140	280	420
Maximum DC Blocking Voltage	V_{DC}	200	400	600
Maximum Average Forward Rectified Current	$I_{F(AV)}$	1.5		
Peak Forward Surge Current, 8.3 ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	I_{FSM}	30		
Maximum Instantaneous Forward Voltage (Note 1)	V_F	@ 1.0 A 1.3		@ 1.5 A 1.4
Maximum Reverse Current @ Rated VR	I_R	$T_A=25\text{ }^\circ\text{C}$ 1		$T_A=100\text{ }^\circ\text{C}$ 10
Pulse energy in avalanche mode, non repetitive (Inductive load switch off)	E_{RSM}	$T_A=25\text{ }^\circ\text{C}$, L=120mH 20		
Maximum Reverse Recovery Time (Note 2)	T_{rr}	75		
Typical Thermal Resistance	$R_{\theta JA}$	100		
Operating Temperature Range	T_J	- 55 to + 150		
Storage Temperature Range	T_{STG}	- 55 to + 150		

Note 1: Pulse Test with PW=300 usec, 1% Duty Cycle

Note 2: Reverse Recovery Test Conditions: $I_F=0.5A$, $I_R=1.0A$, $I_{RR}=0.25A$

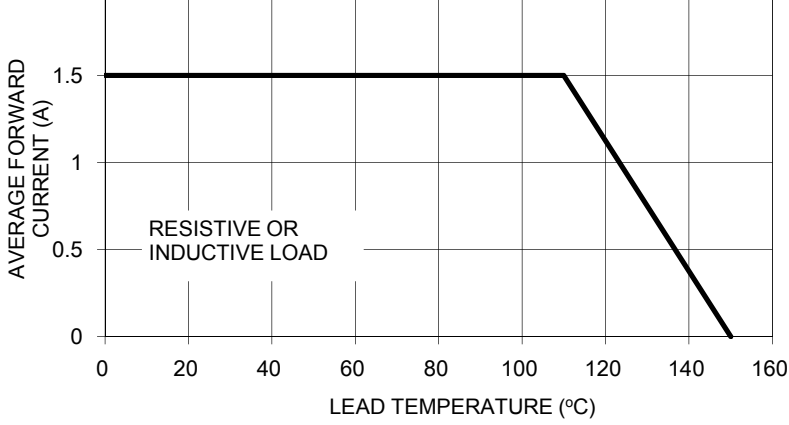


FIG. 3 MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

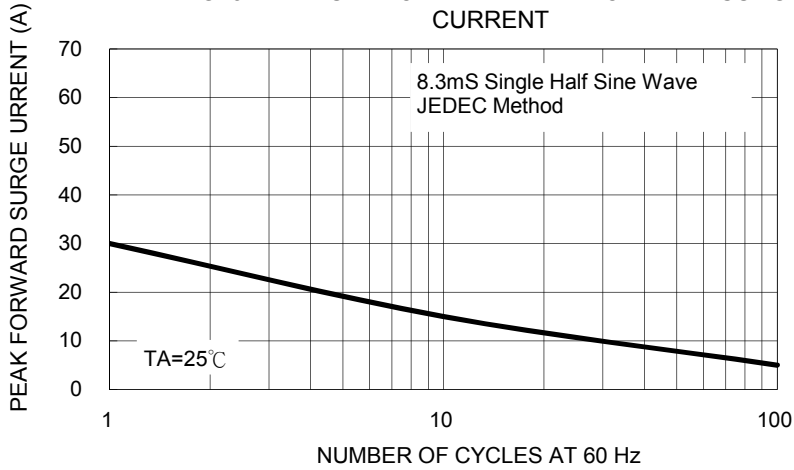


FIG. 4 TYPICAL JUNCTION CAPACITANCE

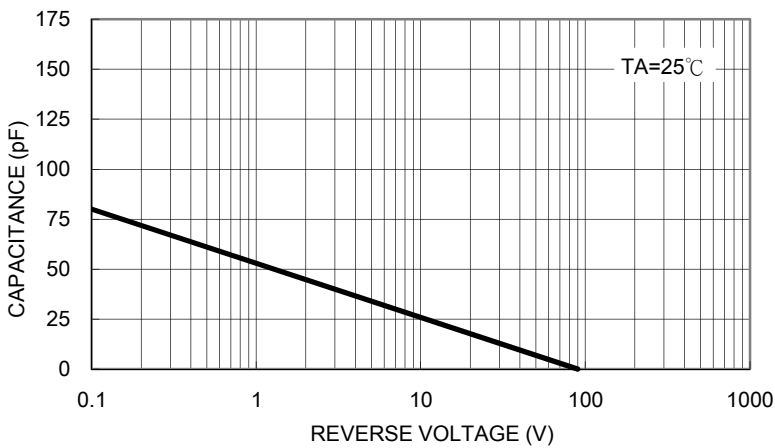
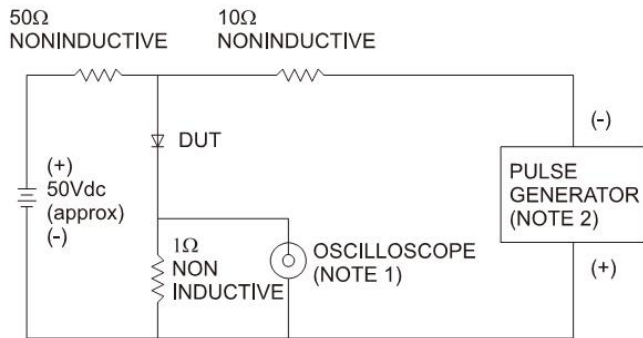


FIG.6- REVERSE RECOVERY TIME CHARACTERISTIC AND TEST CIRCUIT DIAGRAM



NOTES: 1. Rise Time=7ns max. Input Impedance= 1 megohm 22pf
2. Rise Time=10ns max. Source Impedance= 50 ohms

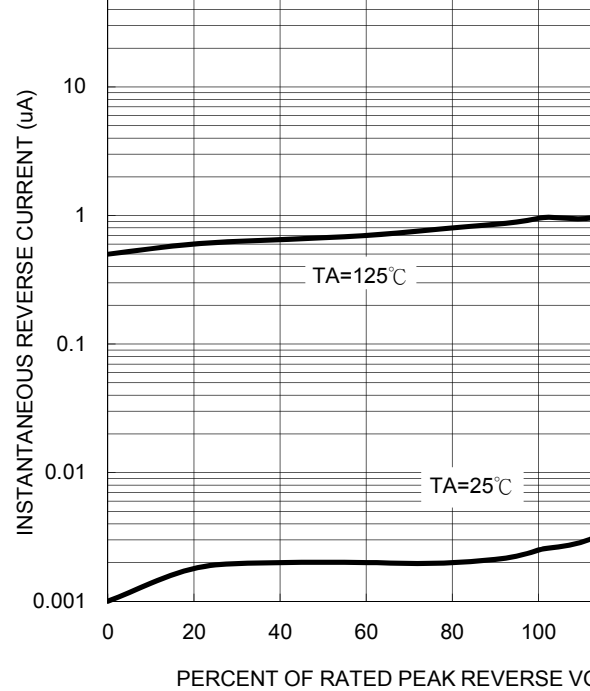
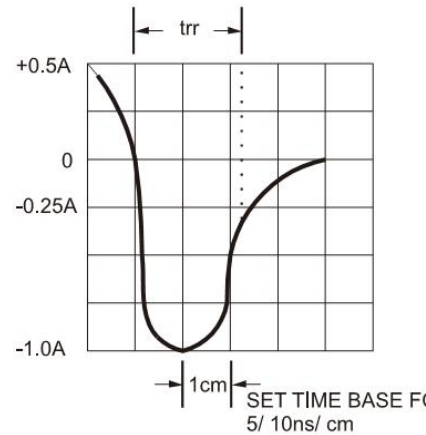
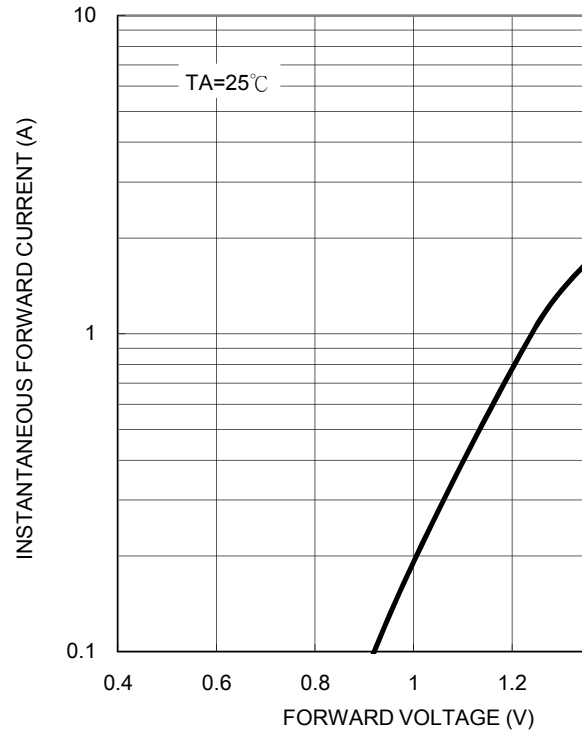


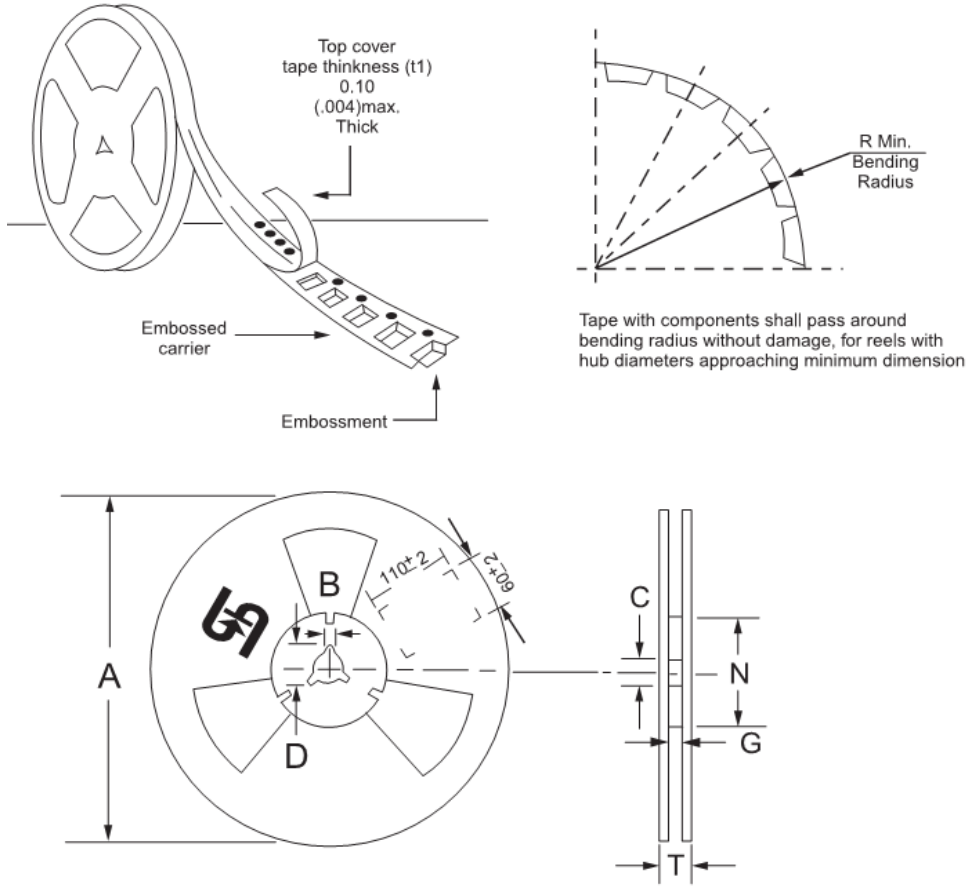
FIG. 5 TYPICAL FORWARD CHARACTERISTIC



BYG20x (Note)	SMA	7.5K / 13" REEL	R2	R2G
	SMA	7.5K / 13" Plastic REEL	M2	M2G
	Folded SMA	1.8K / 7" REEL	F3	F3G
	Folded SMA	7.5K / 13" REEL	F2	F2G
	Folded SMA	7.5K / 13" Plastic REEL	F4	F4G
	C SMA	1.8K / 7" REEL	E3	E3G
	C SMA	7.5K / 13" REEL	E2	E2G

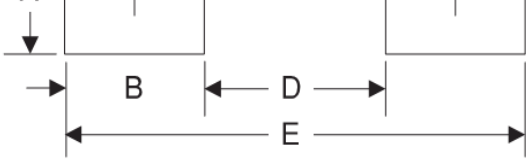
Note: "x" is Device Code from "D" thru "J".

Tape & Reel specification



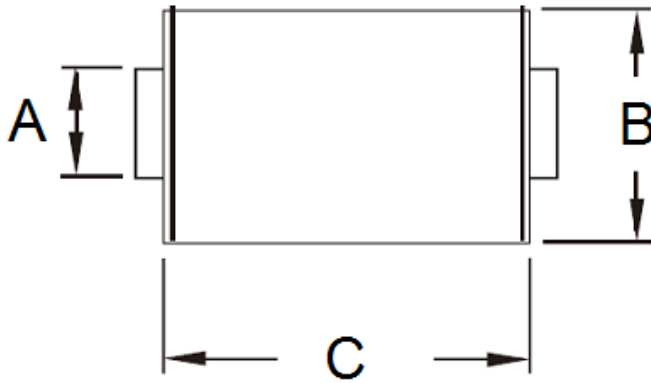
Reel Size	Tape Size	A	B	C	D	N	G	T
		±2.0	±0.4	+0.5;-0.2	min	±1.0	+0.8;-0	max
7"	12mm	178	1.9	13	21	62	12.2	14.6
Reel Size	Tape Size	A	B	C	D	N	G	T
		max	±0.5	±0.5	min	±0.5	+2.0;-0	max
13"	12mm	330	2	13	20.2	75	12.4	18.4

Unit (mm)

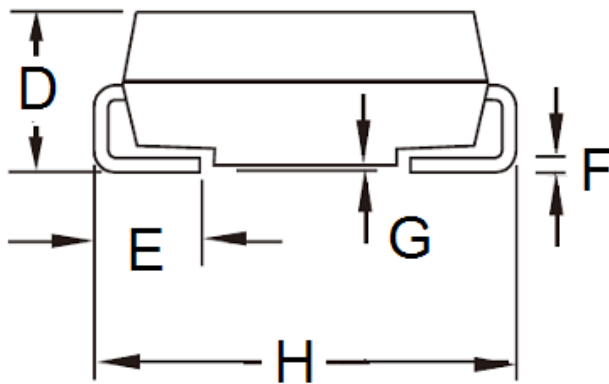


A	1.78
B	1.51
C	3.92
D	2.41
E	4.43

Package Outline Dimensions



DIM.	Unit(mm)		Unit(inch)	
	Min	Max	Min	Max
A	1.27	1.58	0.050	0.062
B	2.29	2.83	0.090	0.112
C	4.06	4.60	0.160	0.181
D	1.99	2.50	0.078	0.098
E	0.90	1.41	0.035	0.055
F	0.15	0.31	0.006	0.012
G	0.10	0.20	0.004	0.008
H	4.95	5.33	0.195	0.210



Marking Diagram



- P/N = Specific Device Code
- G = Green Compound
- YW = Date Code
- F = Factory Code